Surface Mount Schottky Barrier Rectifier Reverse Voltage - 60 V

Forward Current - 2.0A

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- · Low power loss, high efficiency
- · High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

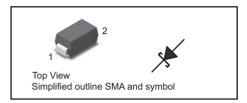
· Case: SMA

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.055g / 0.002oz

PINNING

PIN	DESCRIPTION	
1	Cathode	
2	Anode	



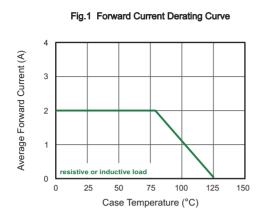
Absolute Maximum Ratings and Electrical characteristics

Ratings at $25\,^{\circ}$ C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by $20\,\%$

Parameter	Symbols	SS26L	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	60	V
Maximum RMS voltage	V _{RMS}	42	V
Maximum DC Blocking Voltage	V _{DC}	60	V
Maximum Average Forward Rectified Current @ Fig.1	I _{F(AV)}	2.0	Α
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50	Α
Peak Forward Surge Current,1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	100	Α
I ² t Rating for fusing (3ms≤t≤8.3ms)	l ² t	10.3	A ² S
Max Instantaneous Forward Voltage at 2 A	V _F	0.55	V
Maximum DC Reverse Current $T_a = 25^{\circ}C$ at Rated DC Reverse Voltage $T_a = 100^{\circ}C$	I _R	0.3 5	mA
Typical Junction Capacitance (1)	Cj	107	pF
Typical Thermal Resistance (2)	$R_{ heta JA} \ R_{ heta JC} \ R_{ heta JL}$	100 20 25	°C/W
Operating Junction Temperature Range	Tj	-55 ~ +125	°C
Storage Temperature Range	T _{stg}	-55 ~ +150	°C

⁽¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

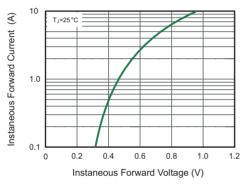
⁽²⁾ P.C.B. mounted with 0.2" X 0.2" (5 X 5 mm) copper pad areas.



None of the state of the state

Fig.2 Typical Reverse Characteristics

Fig.3 Typical Forward Characteristic



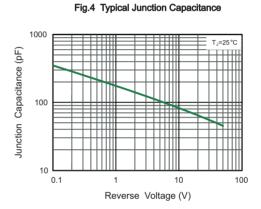
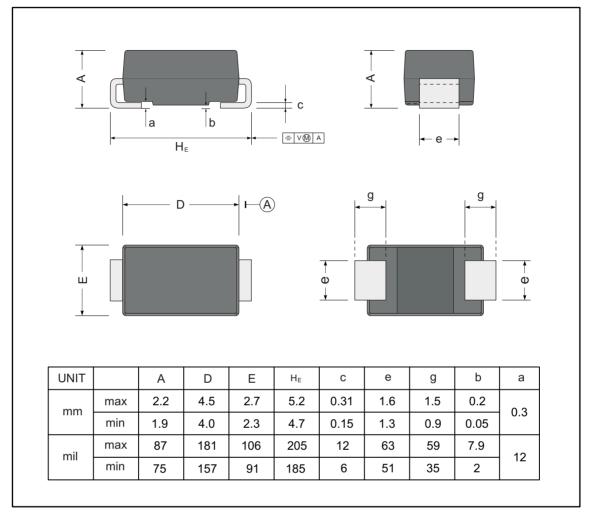


Fig.5 Maximum Non-Repetitive Peak

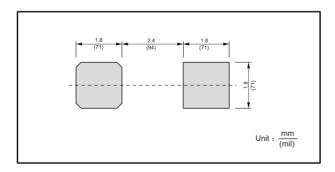
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size



Marking

Type number	Marking code
SS26L	SS26L

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